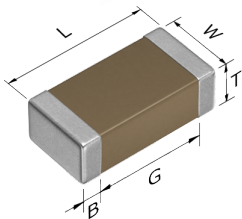


CGB3C1X5R0J106M065AC



TDK item description CGB3C1X5R0J106MT****

Applications	Commercial Grade
Feature	Low Profile
Series	CGB3(1608) [EIA 0603]
Status	Production



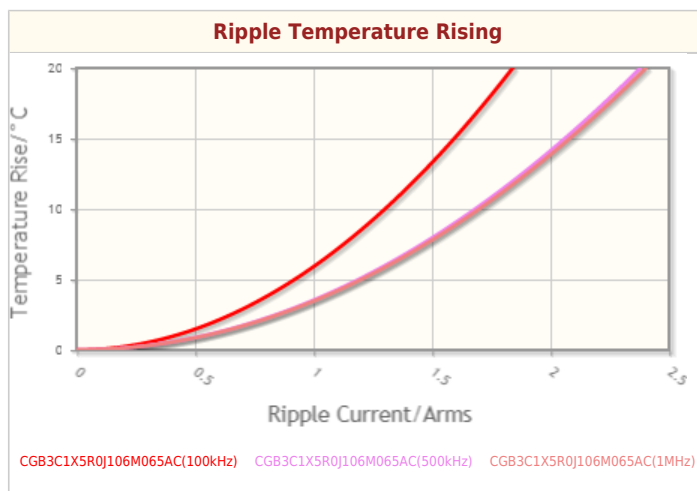
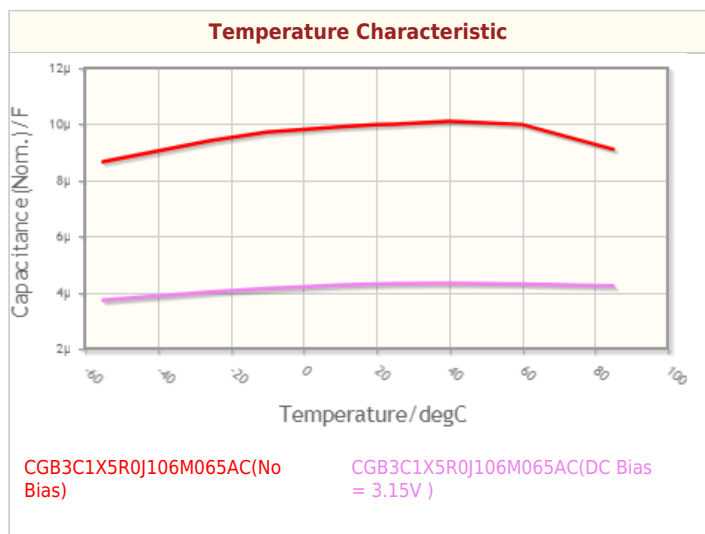
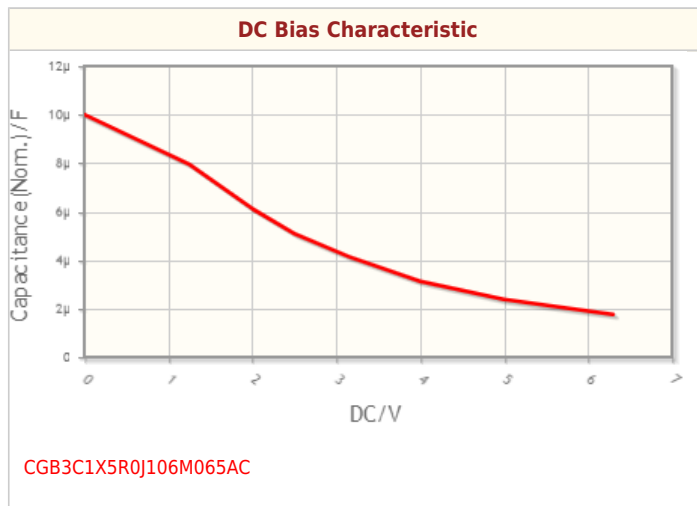
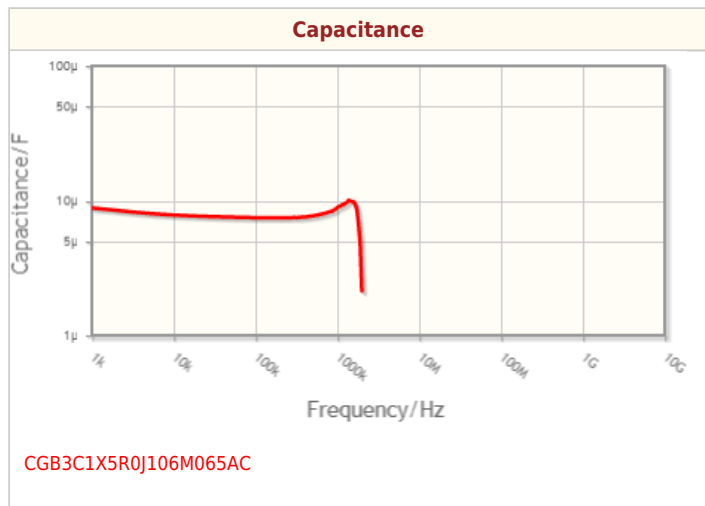
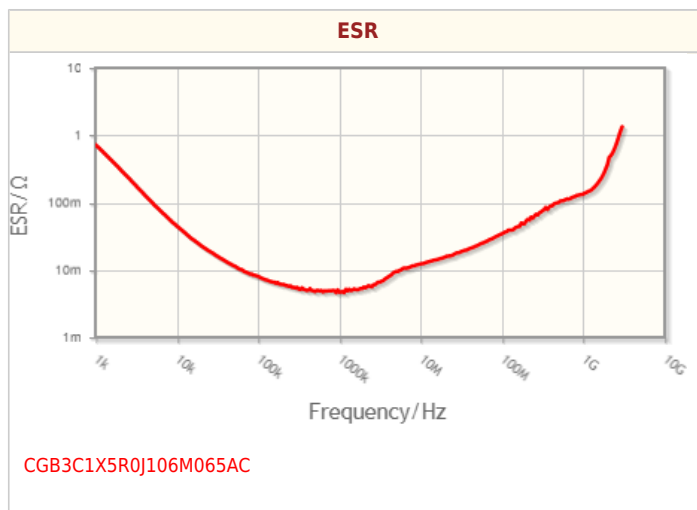
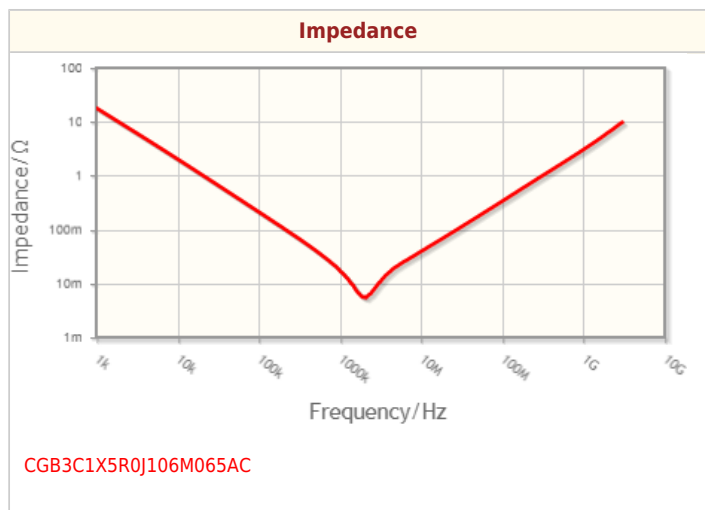
Size	
Length(L)	1.60mm +0.20,-0.10mm
Width(W)	0.80mm +0.20,-0.10mm
Thickness(T)	0.60mm ±0.05mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	10μF ±20%
Rated Voltage	6.3VDC
Temperature Characteristic	X5R(±15%)
Dissipation Factor (Max.)	10%
Insulation Resistance (Min.)	10MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

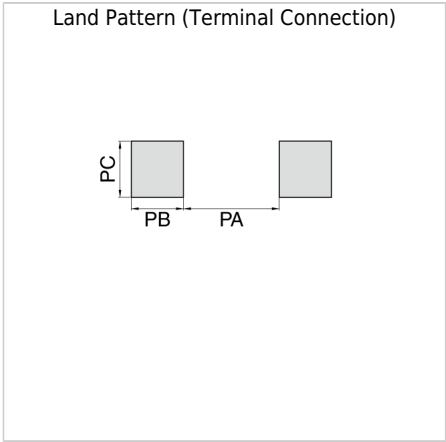


Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)





Associated Images



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.